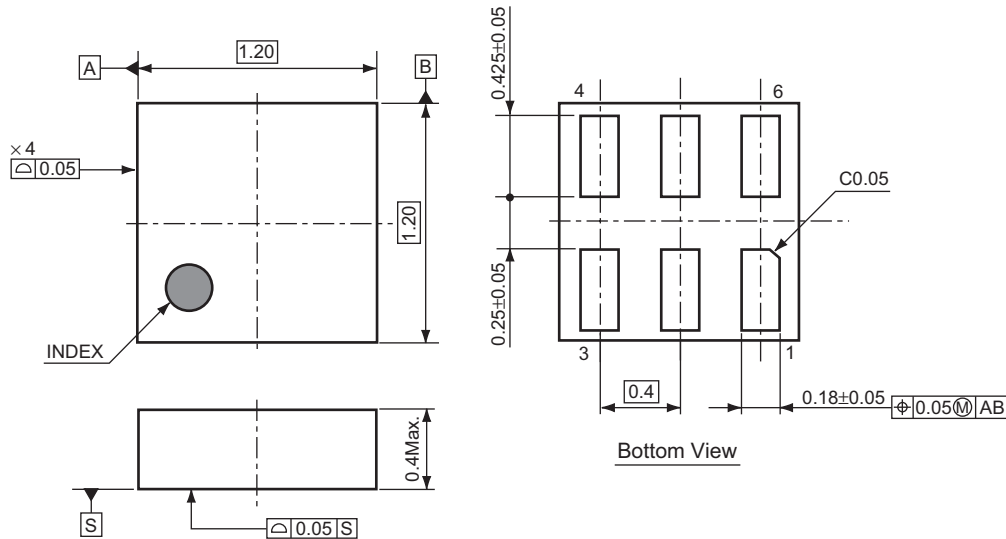


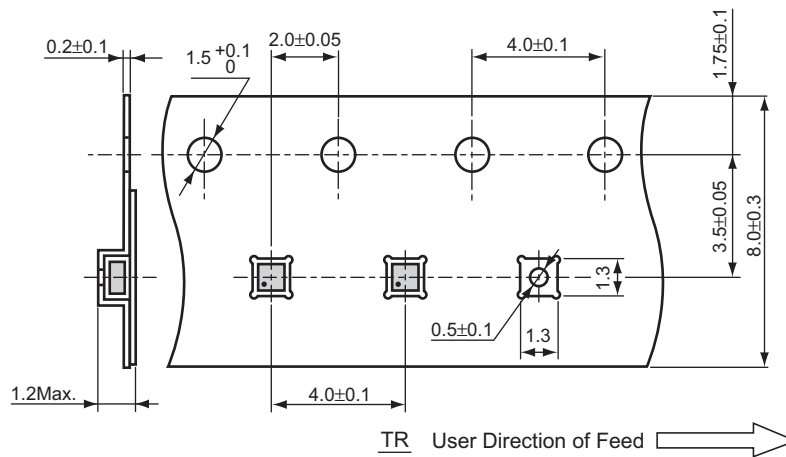
• DFN(PLP)1212-6F

Unit: mm

PACKAGE DIMENSIONS

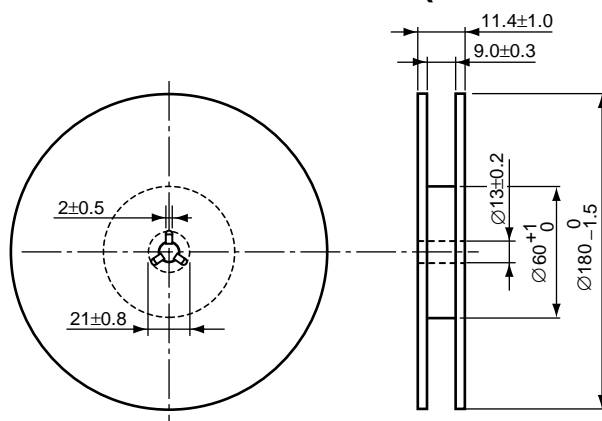


TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-08Bc)

(1reel=5,000pcs)



POWER DISSIPATION (DFN(PLP)1212-6F)

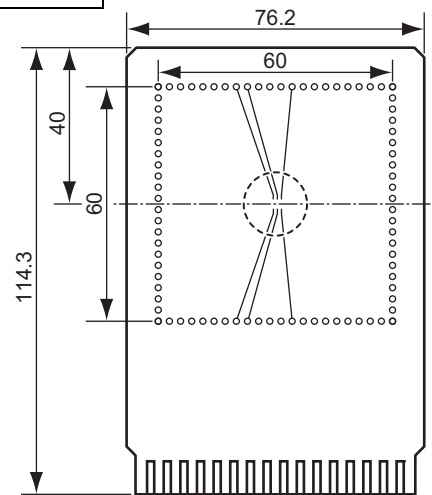
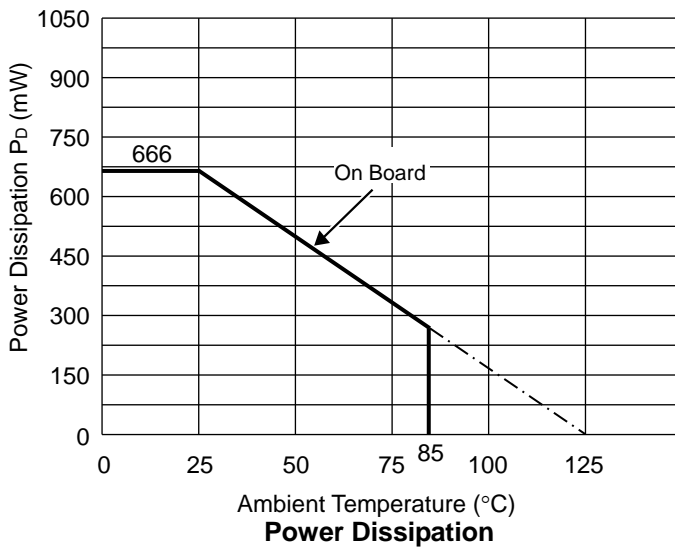
Power Dissipation (P_D) depends on conditions of mounting on board.
 This specification is based on the measurement at the condition below:

Measurement Conditions

	JEDEC STD 51-7 Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (4Layer)
Board Dimensions	76.2mm×114.3mm × 1.6mm
Copper Ratio	Top side, Back side : 60mm square : Approx.10% 2nd, 3rd Layer: 74.2mm×74.2mm: Approx. 100%
Through-holes	φ 0.85mm x 44pcs

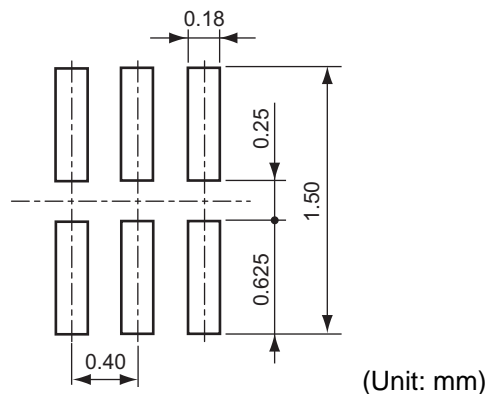
Measurement Results (T_{opt}=25°C, T_{jmax}=125°C)

	JEDEC STD 51-7 Land Pattern
Power Dissipation	666mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}\text{C})/0.666\text{W}=150^{\circ}\text{C/W}$
	$\theta_{jc}=28^{\circ}\text{C/W}$



Measurement Board Pattern
 ○ IC Mount Area (Unit: mm)

RECOMMENDED LAND PATTERN



(Unit: mm)